T-1 3/4 (5mm) BI-LEVEL LED INDICATOR

Part Number: WP1503EB/2YD Yellow

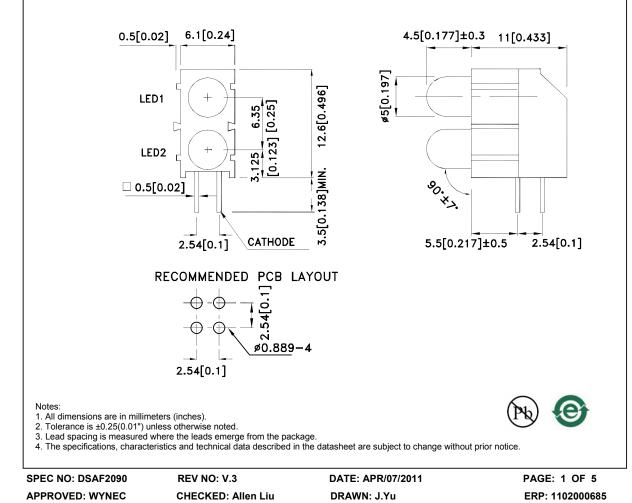
Features

- Pre-trimmed leads for pc board mounting.
- Stackable units.
- Colors can be mixed in a single housing.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

Description

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

Package Dimensions



Selection Guide										
Part No.		Dice	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]				
				Min.	Тур.	201/2				
WP1503EE	3/2YD	Yellow (GaAsP/GaP)	Yellow Diffused	15	30	60°				

Notes:

01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Yellow	590		nm	l⊧=20mA
λD [1]	Dominant Wavelength	Yellow	588		nm	l⊧=20mA
Δλ1/2	Spectral Line Half-width	Yellow	35		nm	l⊧=20mA
С	Capacitance	Yellow	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Yellow	2.1	2.5	V	l⊧=20mA
lr	Reverse Current	Yellow		10	uA	VR = 5V

Notes:

1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

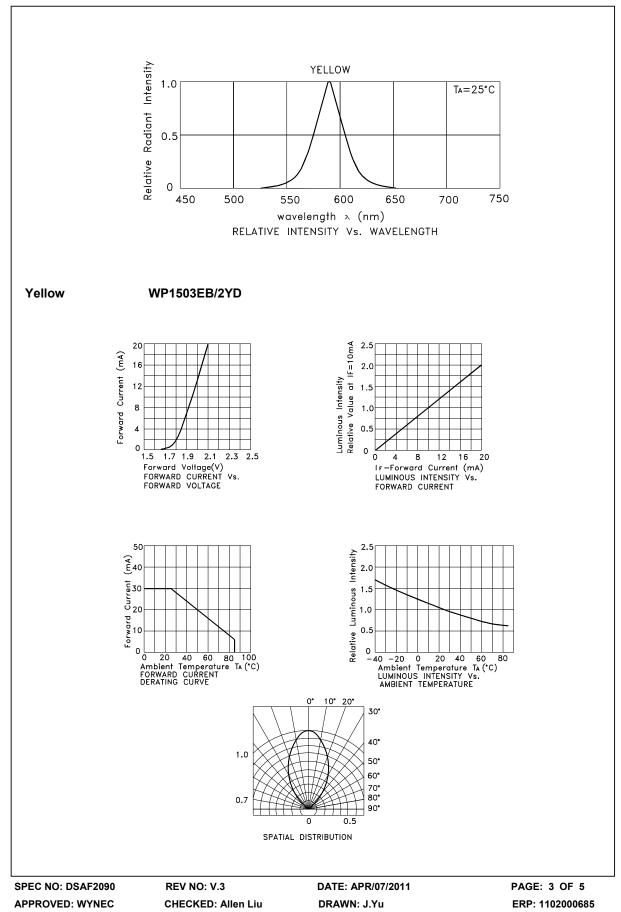
Parameter	Yellow		
Power dissipation	75		
DC Forward Current	30		
Peak Forward Current [1]	140	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [2]	260°C For 3 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds		
Notes: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.			

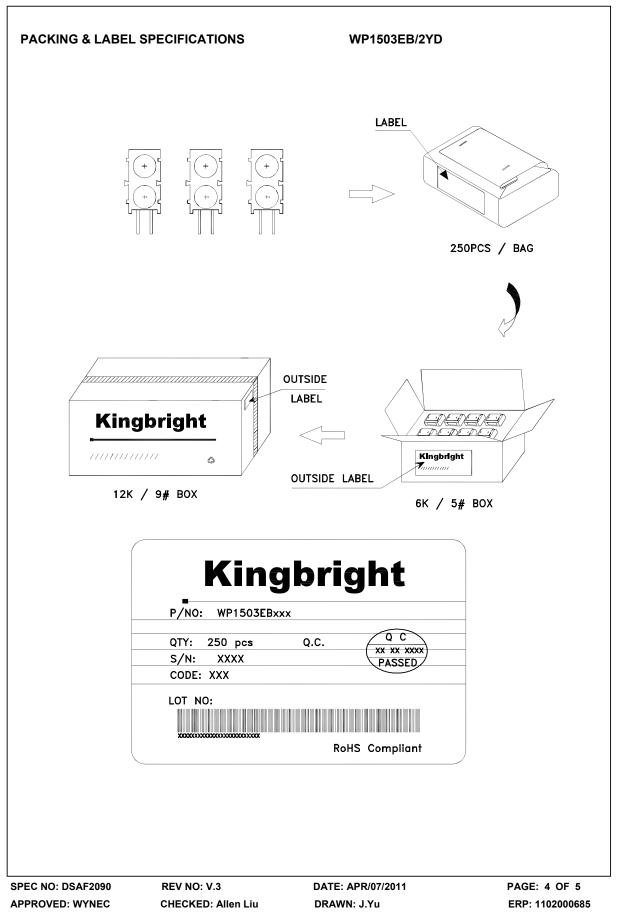
2. 2mm below package base.
3. 5mm below package base.

SPEC NO: DSAF2090 APPROVED: WYNEC

REV NO: V.3 CHECKED: Allen Liu DATE: APR/07/2011 DRAWN: J.Yu

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PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

